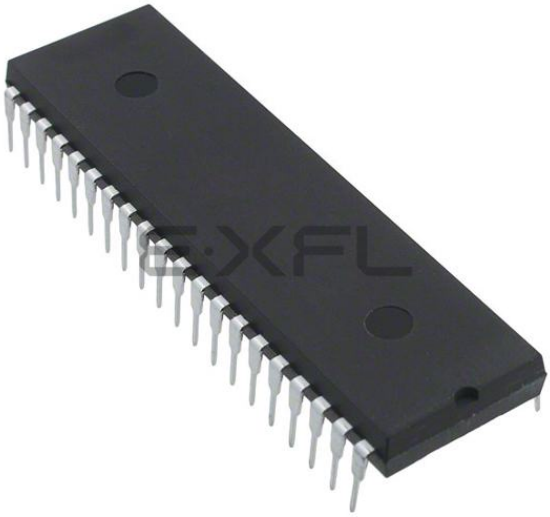

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc64a-04-p

3.1 Clocking Scheme/Instruction Cycle

The clock input (from OSC1) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3, and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clock and instruction execution flow is shown in Figure 3-5.

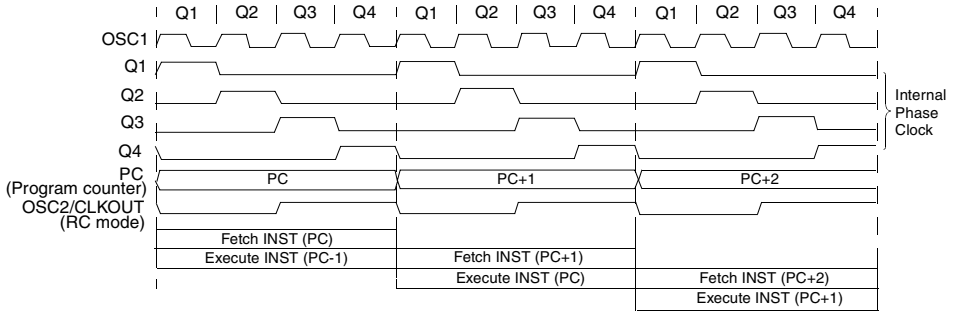
3.2 Instruction Flow/Pipelining

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3, and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g. `GOTO`) then two cycles are required to complete the instruction (Example 3-1).

A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register (IR)" in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 3-5: CLOCK/INSTRUCTION CYCLE



EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW

	Tcy0	Tcy1	Tcy2	Tcy3	Tcy4	Tcy5
1. MOVLW 55h	Fetch 1	Execute 1				
2. MOVWF PORTB		Fetch 2	Execute 2			
3. CALL SUB_1			Fetch 3	Execute 3		
4. BSF PORTA, BIT3 (Forced NOP)				Fetch 4	Flush	
5. Instruction @ address SUB_1					Fetch SUB_1	Execute SUB_1

All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is "flushed" from the pipeline while the new instruction is being fetched and then executed.

TABLE 4-6: SPECIAL FUNCTION REGISTERS FOR THE PIC16C66/67 (Cont.'d)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets(3)
Bank 2											
100h(1)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000
101h	TMR0	Timer0 module's register								xxxx xxxx	uuuu uuuu
102h(1)	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
103h(1)	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
104h(1)	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
105h	—	Unimplemented								—	—
106h	PORTB	PORTB Data Latch when written: PORTB pins when read								xxxx xxxx	uuuu uuuu
107h	—	Unimplemented								—	—
108h	—	Unimplemented								—	—
109h	—	Unimplemented								—	—
10Ah(1,2)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000
10Bh(1)	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
10Ch-10Fh	—	Unimplemented								—	—
Bank 3											
180h(1)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000
181h	OPTION	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
182h(1)	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
183h(1)	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
184h(1)	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
185h	—	Unimplemented								—	—
186h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
187h	—	Unimplemented								—	—
188h	—	Unimplemented								—	—
189h	—	Unimplemented								—	—
18Ah(1,2)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000
18Bh(1)	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
18Ch-19Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.
2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)
3: Other (non power-up) resets include external reset through $\overline{MCLR}$ and the Watchdog Timer reset.
4: PIE1<6> and PIR1<6> are reserved on the PIC16C66/67, always maintain these bits clear.
5: PORTD, PORTE, TRISD, and TRISE are not implemented on the PIC16C66, read as '0'.
6: PSPIF (PIR1<7>) and PSPIE (PIE1<7>) are reserved on the PIC16C66, maintain these bits clear.

FIGURE 4-15: PIE1 REGISTER FOR PIC16C65/65A/R65/67 (ADDRESS 8Ch)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PSPIE	—	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **PSPIE:** Parallel Slave Port Read/Write Interrupt Enable bit
1 = Enables the PSP read/write interrupt
0 = Disables the PSP read/write interrupt

bit 6: **Reserved:** Always maintain this bit clear.

bit 5: **RCIE:** USART Receive Interrupt Enable bit
1 = Enables the USART receive interrupt
0 = Disables the USART receive interrupt

bit 4: **TXIE:** USART Transmit Interrupt Enable bit
1 = Enables the USART transmit interrupt
0 = Disables the USART transmit interrupt

bit 3: **SSPIE**: Synchronous Serial Port Interrupt Enable bit
1 = Enables the SSP interrupt
0 = Disables the SSP interrupt

bit 2: **CCP1IE**: CCP1 Interrupt Enable bit
1 = Enables the CCP1 interrupt
0 = Disables the CCP1 interrupt

bit 1: **TMR2IE**: TMR2 to PR2 Match Interrupt Enable bit
1 = Enables the TMR2 to PR2 match interrupt
0 = Disables the TMR2 to PR2 match interrupt

bit 0: **TMR1IE**: TMR1 Overflow Interrupt Enable bit
1 = Enables the TMR1 overflow interrupt
0 = Disables the TMR1 overflow interrupt

FIGURE 4-18: PIR1 REGISTER FOR PIC16C64/64A/R64 (ADDRESS 0Ch)

R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
PSPIF	—	—	—	SSPIF	CCP1IF	TMR2IF	TMR1IF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **PSPIF:** Parallel Slave Port Interrupt Flag bit
1 = A read or a write operation has taken place (must be cleared in software)
0 = No read or write operation has taken place

bit 6: **Reserved**: Always maintain this bit clear.

bit 5-4: **Unimplemented**: Read as '0'

bit 3: **SSPIF**: Synchronous Serial Port Interrupt Flag bit
1 = The transmission/reception is complete (must be cleared in software)
0 = Waiting to transmit/receive

bit 2: **CCP1IF**: CCP1 Interrupt Flag bit
Capture Mode
1 = A TMR1 register capture occurred (must be cleared in software)
0 = No TMR1 register capture occurred
Compare Mode
1 = A TMR1 register compare match occurred (must be cleared in software)
0 = No TMR1 register compare match occurred
PWM Mode
Unused in this mode

bit 1: **TMR2IF**: TMR2 to PR2 Match Interrupt Flag bit
1 = TMR2 to PR2 match occurred (must be cleared in software)
0 = No TMR2 to PR2 match occurred

bit 0: **TMR1IF**: TMR1 Overflow Interrupt Flag bit
1 = TMR1 register overflow occurred (must be cleared in software)
0 = No TMR1 register occurred

Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

10.0 CAPTURE/COMPARE/PWM (CCP) MODULE(s)

Applicable Devices														
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	**CCP1**
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	**CCP2**

Each CCP (Capture/Compare/PWM) module contains a 16-bit register which can operate as a 16-bit capture register, as a 16-bit compare register, or as a PWM master/slave duty cycle register. Both the CCP1 and CCP2 modules are identical in operation, with the exception of the operation of the special event trigger. Table 10-1 and Table 10-2 show the resources and interactions of the CCP modules(s). In the following sections, the operation of a CCP module is described with respect to CCP1. CCP2 operates the same as CCP1, except where noted.

CCP1 module:

Capture/Compare/PWM Register1 (CCPR1) is comprised of two 8-bit registers: CCPR1L (low byte) and CCPR1H (high byte). The CCP1CON register controls the operation of CCP1. All are readable and writable.

CCP2 module:

Capture/Compare/PWM Register2 (CCPR2) is comprised of two 8-bit registers: CCPR2L (low byte) and CCPR2H (high byte). The CCP2CON register controls the operation of CCP2. All are readable and writable.

For use of the CCP modules, refer to the *Embedded Control Handbook,* "Using the CCP Modules" (AN594).

TABLE 10-1: CCP MODE - TIMER RESOURCE

CCP Mode	Timer Resource
Capture	Timer1
Compare	Timer1
PWM	Timer2

TABLE 10-2: INTERACTION OF TWO CCP MODULES

CCPx Mode	CCPy Mode	Interaction
Capture	Capture	Same TMR1 time-base.
Capture	Compare	The compare should be configured for the special event trigger, which clears TMR1.
Compare	Compare	The compare(s) should be configured for the special event trigger, which clears TMR1.
PWM	PWM	The PWMs will have the same frequency, and update rate (TMR2 interrupt).
PWM	Capture	None
PWM	Compare	None

FIGURE 11-13: SPI MODE TIMING (SLAVE MODE WITH CKE = 1) (PIC16C66/67)

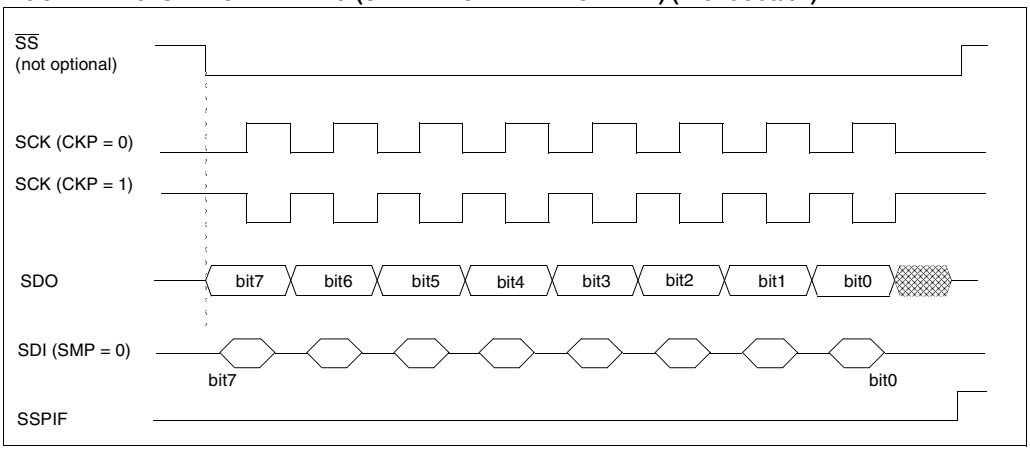


TABLE 11-2: REGISTERS ASSOCIATED WITH SPI OPERATION (PIC16C66/67)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
85h	TRISA	—	—	PORTA Data Direction register						--11 1111	--11 1111
87h	TRISC	PORTC Data Direction register								1111 1111	1111 1111
94h	SSPSTAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'.
Shaded cells are not used by SSP module in SPI mode.

Note 1: PSPIF and PSPIE are reserved on the PIC16C66, always maintain these bits clear.
2: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

12.1.1 SAMPLING

The data on the RC7/RX/DT pin is sampled three times by a majority detect circuit to determine if a high or a low level is present at the RX pin. If bit BRGH (TXSTA<2>) is clear (i.e., at the low baud rates), the sampling is done on the seventh, eighth and ninth falling edges of a x16 clock (Figure 12-3). If bit BRGH is set (i.e., at the high baud rates), the sampling is done on the 3 clock edges preceding the second rising edge after the first falling edge of a x4 clock (Figure 12-4 and Figure 12-5).

FIGURE 12-3: RX PIN SAMPLING SCHEME (BRGH = 0) PIC16C63/R63/65/65A/R65)

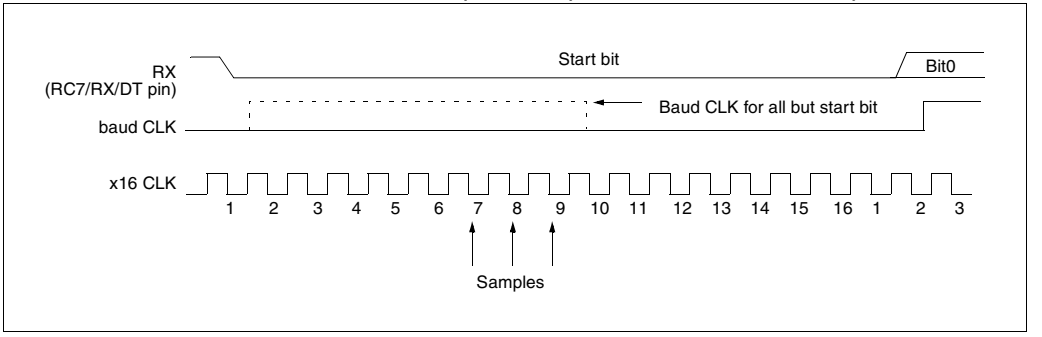


FIGURE 12-4: RX PIN SAMPLING SCHEME (BRGH = 1) (PIC16C63/R63/65/65A/R65)

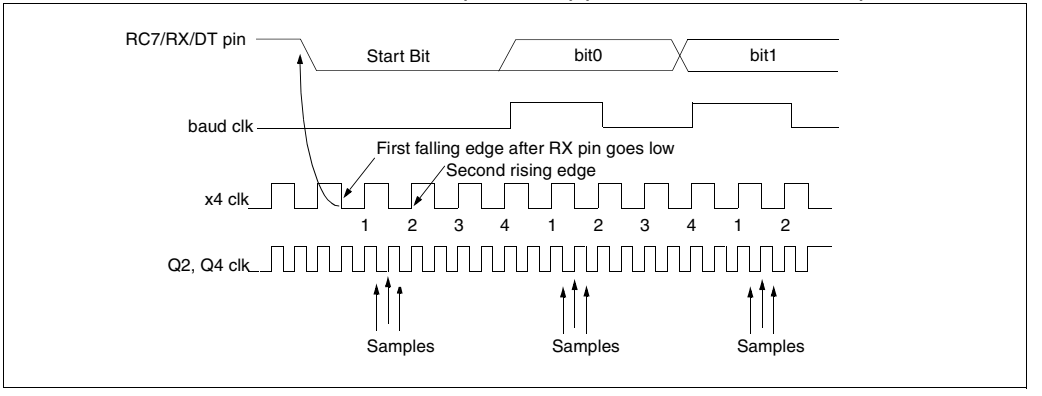
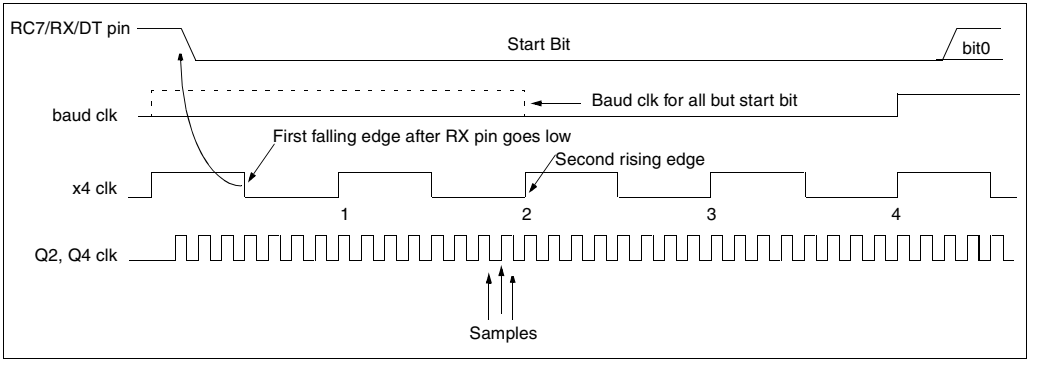


FIGURE 12-5: RX PIN SAMPLING SCHEME (BRGH = 1) (PIC16C63/R63/65/65A/R65)



13.4 Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST) and Brown-out Reset (BOR)

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

13.4.1 POWER-ON RESET (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.5V - 2.1V). To take advantage of the POR, just tie the $\overline{MCLR}$/VPP pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is required. See Electrical Specifications for details.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, ...) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met. Brown-out Reset may be used to meet the startup conditions.

For additional information, refer to Application Note AN607, "*Power-up Trouble Shooting*."

13.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only, from POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

13.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures the crystal oscillator or resonator has started and stabilized.

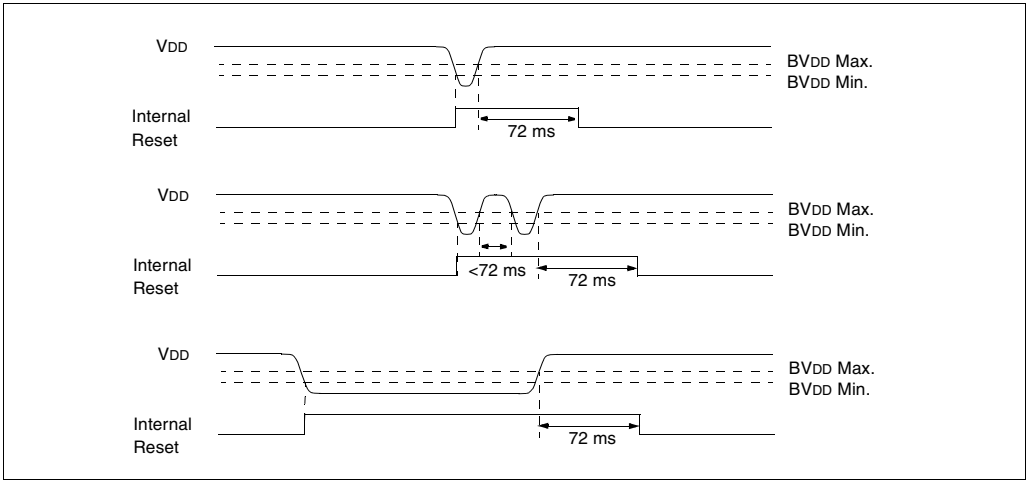
The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

13.4.4 BROWN-OUT RESET (BOR)

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

A configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V (parameter D005 in Electrical Specification section) for greater than parameter #34 (see Electrical Specification section), the brown-out situation will reset the chip. A reset may not occur if VDD falls below 4.0V for less than parameter #34. The chip will remain in Brown-out Reset until VDD rises above BVDD. The Power-up Timer will now be invoked and will keep the chip in RESET an additional 72 ms. If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above BVDD, the Power-up Timer will execute a 72 ms time delay. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 13-10 shows typical brown-out situations.

FIGURE 13-10: BROWN-OUT SITUATIONS



13.5.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered: either rising if edge select bit INTEDG (OPTION<6>) is set, or falling, if bit INTEDG is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). The INTF bit must be cleared in software in the interrupt service routine before re-enabling this interrupt. The INT interrupt can wake the processor from SLEEP, if enable bit INTE was set prior to going into SLEEP. The status of global enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See Section 13.8 for details on SLEEP mode.

13.5.2 TMR0 INTERRUPT

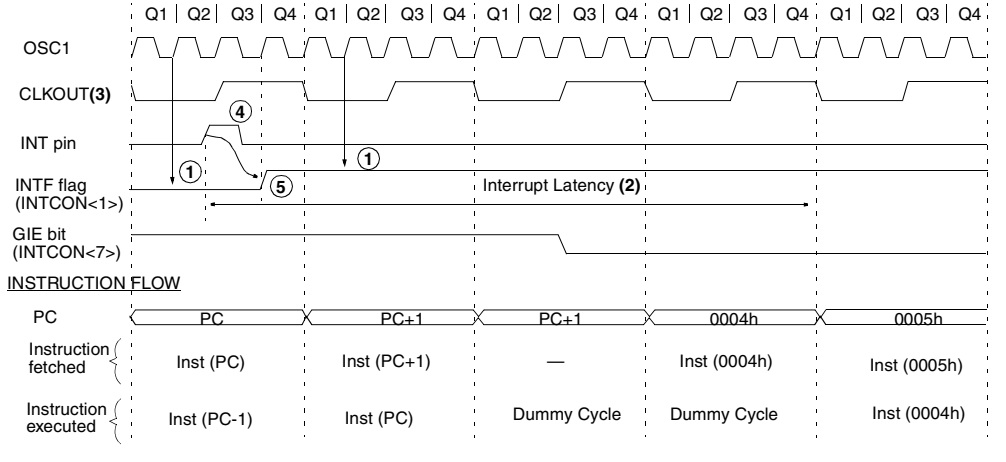
An overflow (FFh → 00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>) (Section 7.0).

13.5.3 PORTB INTERRUPT ON CHANGE

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>) (Section 5.2).

Note:	For the PIC16C61/62/64/65, if a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then flag bit RBIF may not get set.

FIGURE 13-19: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Interrupt latency = 3TCY for synchronous interrupt and 3-4TCY for asynchronous interrupt. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT is available only in RC oscillator mode.

4: For minimum width spec of INT pulse, refer to AC specs.

5: INTF can to be set anytime during the Q4-Q1 cycles.

14.0 INSTRUCTION SET SUMMARY

Each PIC16CXX instruction is a 14-bit word divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16CXX instruction set summary in Table 14-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 14-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 14-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
PCLATH	Program Counter High Latch
GIE	Global Interrupt Enable bit
WDT	Watchdog Timer/Counter
$\overline{TO}$	Time-out bit
$\overline{PD}$	Power-down bit
dest	Destination either the W register or the specified register file location
[ ]	Options
( )	Contents
→	Assigned to
< >	Register bit field
∈	In the set of
italics	User defined term (font is courier)

The instruction set is highly orthogonal and is grouped into three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs.

Table 14-2 lists the instructions recognized by the MPASM assembler.

Figure 14-1 shows the general formats that the instructions can have.

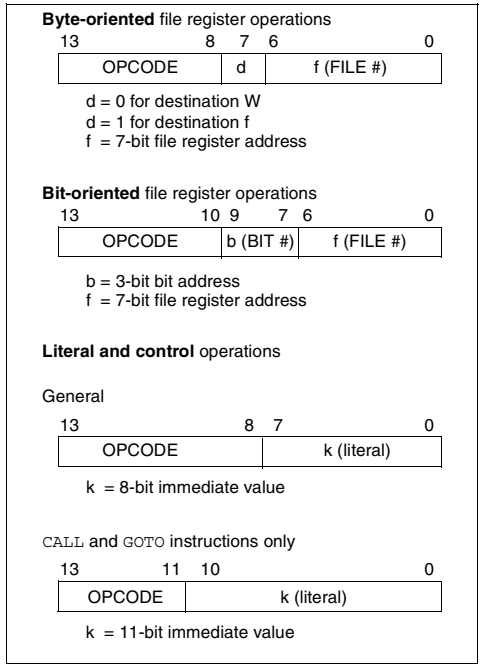
Note: To maintain upward compatibility with future PIC16CXX products, do not use the OPTION and TRIS instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

FIGURE 14-1: GENERAL FORMAT FOR INSTRUCTIONS



BTFSS **Bit Test f, Skip if Set**

Syntax: [*label*] BTFSS f,b

Operands: 0 ≤ f ≤ 127
0 ≤ b < 7

Operation: skip if (f<b>) = 1

Status Affected: None

Encoding:

01	11bb	bfff	ffff

Description: If bit 'b' in register 'f' is '0' then the next instruction is executed.
If bit 'b' is '1', then the next instruction is discarded and a NOP is executed instead, making this a 2TCY instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	No-Operation

If Skip: (2nd Cycle)

Q1	Q2	Q3	Q4
No-Operation	No-Operation	No-Operation	No-Operation

Example

```
HERE    BTFSC   FLAG,1
FALSE   GOTO    PROCESS_CODE
TRUE    •
        •
        •
```

Before Instruction
PC = address HERE
After Instruction
if FLAG<1> = 0,
PC = address FALSE
if FLAG<1> = 1,
PC = address TRUE

CALL **Call Subroutine**

Syntax: [*label*] CALL k

Operands: 0 ≤ k ≤ 2047

Operation: (PC)+ 1→ TOS,
k → PC<10:0>,
(PCLATH<4:3>) → PC<12:11>

Status Affected: None

Encoding:

10	0kkk	kkkk	kkkk

Description: Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a two cycle instruction.

Words: 1

Cycles: 2

Q Cycle Activity:

	Q1	Q2	Q3	Q4
1st Cycle	Decode	Read literal 'k', Push PC to Stack	Process data	Write to PC
2nd Cycle	No-Operation	No-Operation	No-Operation	No-Operation

Example

```
HERE    CALL    THERE
```

Before Instruction
PC = Address HERE
After Instruction
PC = Address THERE
TOS = Address HERE+1

SLEEP

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → $\overline{TO}$,
0 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

00	0000	0110	0011

Description: The power-down status bit, $\overline{PD}$ is cleared. Time-out status bit, $\overline{TO}$ is set. Watchdog Timer and its prescaler are cleared.
The processor is put into SLEEP mode with the oscillator stopped. See Section 13.8 for more details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No-Operation	No-Operation	Go to Sleep

Example: `SLEEP`

SUBLW Subtract W from Literal

Syntax: [*label*] SUBLW k

Operands: 0 ≤ k ≤ 255

Operation: k - (W) → (W)

Status Affected: C, DC, Z

Encoding:

11	110x	kkkk	kkkk

Description: The W register is subtracted (2's complement method) from the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example 1: `SUBLW 0x02`

Before Instruction
W = 1
C = ?
Z = ?

After Instruction
W = 1
C = 1; result is positive
Z = 0

Example 2: Before Instruction
W = 2
C = ?
Z = ?

After Instruction
W = 0
C = 1; result is zero
Z = 1

Example 3: Before Instruction
W = 3
C = ?
Z = ?

After Instruction
W = 0xFF
C = 0; result is negative
Z = 0

Applicable Devices 61 | 62 | 62A | R62 | 63 | R63 | 64 | 64A | R64 | 65 | 65A | R65 | 66 | 67

15.5 Timing Diagrams and Specifications

FIGURE 15-2: EXTERNAL CLOCK TIMING

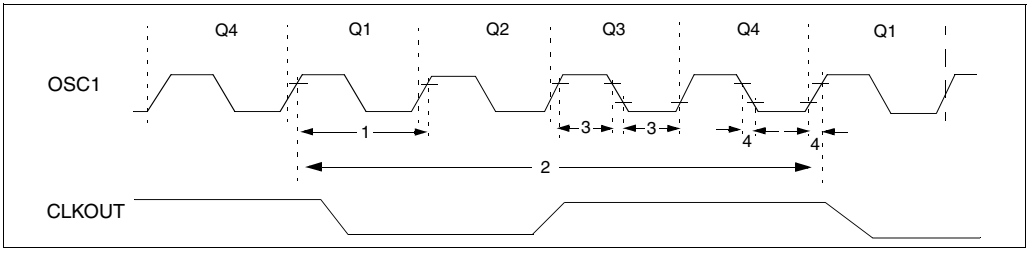


TABLE 15-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	**External CLKIN Frequency (Note 1)**	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			1	—	4	MHz	HS osc mode (-04)
			1	—	20	MHz	HS osc mode (-20)
1	Tosc	**External CLKIN Period (Note 1)**	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	1,000	ns	HS osc mode (-04)
			50	—	1,000	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	1.0	TCY	DC	µs	TCY = 4/Fosc
3	TosL, TosH	**External Clock in (OSC1) High or Low Time**	50	—	—	ns	XT oscillator
			2.5	—	—	µs	LP oscillator
			10	—	—	ns	HS oscillator
4	TosR, TosF	**External Clock in (OSC1) Rise or Fall Time**	25	—	—	ns	XT oscillator
			50	—	—	ns	LP oscillator
			15	—	—	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

19.2 DC Characteristics: PIC16LC65-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial				
Param No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	Supply Voltage	VDD	3.0	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	105	µA	LP osc configuration FOSC = 32 kHz, VDD = 4.0V, WDT disabled
D020	Power-down Current (Note 3, 5)	IPD	-	7.5	800	µA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021			-	0.9	800	µA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	800	µA	VDD = 3.0V, WDT disabled, -40°C to +85°C

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

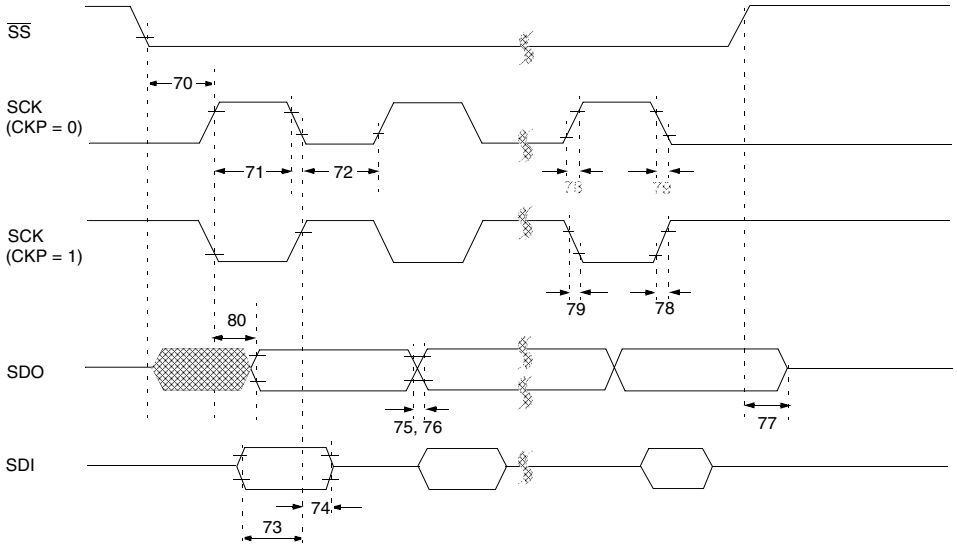
2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

FIGURE 21-9: SPI MODE TIMING



Note: Refer to Figure 21-1 for load conditions

TABLE 21-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{SS}$↓ to SCK↓ or SCK↑ input	TCY	—	—	ns	
71*	TscH	SCK input high time (slave mode)	TCY + 20	—	—	ns	
72*	TscL	SCK input low time (slave mode)	TCY + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	—	—	ns	
75*	TdoR	SDO data output rise time	—	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	$\overline{SS}$↑ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

22.0 ELECTRICAL CHARACTERISTICS FOR PIC16C66/67

Absolute Maximum Ratings (†)

Ambient temperature under bias ..... -55°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, $\overline{MCLR}$, and RA4) ..... -0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS ..... -0.3V to +7.5V
Voltage on $\overline{MCLR}$ with respect to VSS (Note 2) ..... 0V to +14V
Voltage on RA4 with respect to Vss ..... 0V to +14V
Total power dissipation (Note 1) 1.0W
Maximum current out of VSS pin ..... 300 mA
Maximum current into VDD pin ..... 250 mA
Input clamp current, IIK (VI < 0 or VI > VDD) ..... ±20 mA
Output clamp current, IOK (VO < 0 or VO > VDD) ..... ±20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (Note 3) (combined) ..... 200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (Note 3) (combined) ..... 200 mA
Maximum current sunk by PORTC and PORTD (Note 3) (combined) ..... 200 mA
Maximum current sourced by PORTC and PORTD (Note 3) (combined) ..... 200 mA

Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - $\sum$ IOH} + $\sum$ {(VDD-VOH) x IOH} + $\sum$(VOl x IOL)

Note 2: Voltage spikes below VSS at the $\overline{MCLR}$/VPP pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$/VPP pin rather than pulling this pin directly to VSS.

Note 3: PORTD and PORTE not available on the PIC16C66.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 22-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

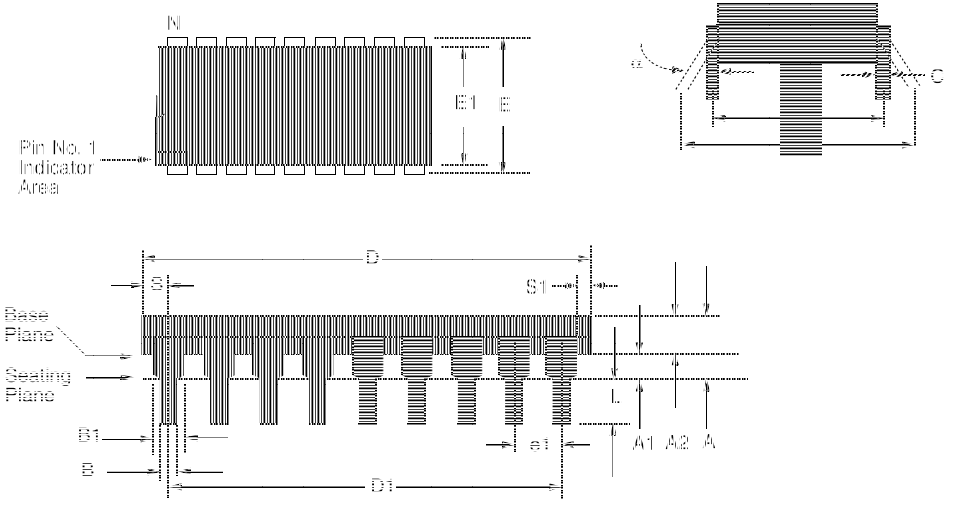
OSC	PIC16C66-04 PIC16C67-04	PIC16C66-10 PIC16C67-10	PIC16C66-20 PIC16C67-20	PIC16LC66-04 PIC16LC67-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.
XT	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 10 mA max. at 5.5V IPD 1.5 μA typ. at 4.5V Freq: 10 MHz max.	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 52.5 μA typ. at 32 kHz, 4.0V IPD: 0.9 μA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 2.5V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.	VDD: 2.5V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

24.0 PACKAGING INFORMATION

24.1 18-Lead Plastic Dual In-line (300 mil) (P)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

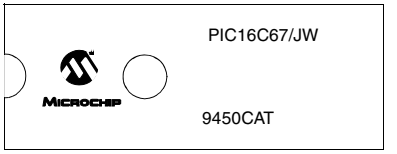


Package Group: Plastic Dual In-Line (PLA)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	–	4.064		–	0.160	
A1	0.381	–		0.015	–	
A2	3.048	3.810		0.120	0.150	
B	0.355	0.559		0.014	0.022	
B1	1.524	1.524	**Reference**	0.060	0.060	**Reference**
C	0.203	0.381	**Typical**	0.008	0.015	**Typical**
D	22.479	23.495		0.885	0.925	
D1	20.320	20.320	**Reference**	0.800	0.800	**Reference**
E	7.620	8.255		0.300	0.325	
E1	6.096	7.112		0.240	0.280	
e1	2.489	2.591	**Typical**	0.098	0.102	**Typical**
eA	7.620	7.620	**Reference**	0.300	0.300	**Reference**
eB	7.874	9.906		0.310	0.390	
L	3.048	3.556		0.120	0.140	
N	18	18		18	18	
S	0.889	–		0.035	–	
S1	0.127	–		0.005	–	

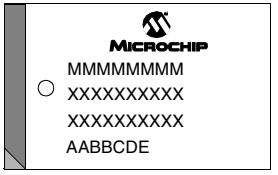
Package Marking Information (Cont'd)

40-Lead CERDIP Windowed

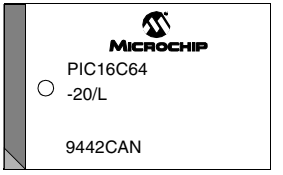
Example



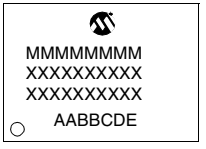
44-Lead PLCC



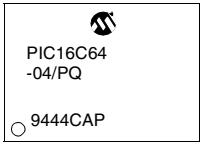
Example



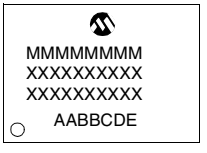
44-Lead MQFP



Example



44-Lead TQFP



Example

Legend:	MM...M	Microchip part number information
	XX...X	Customer specific information*
	AA	Year code (last 2 digits of calender year)
	BB	Week code (week of January 1 is week '01')
	C	Facility code of the plant at which wafer is manufactured. C = Chandler, Arizona, U.S.A. S = Tempe, Arizona, U.S.A.
	D_1	Mask revision number for microcontroller
	E	Assembly code of the plant or country of origin in which part was assembled.
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.	

* Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask revision number, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

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LIST OF EQUATION AND EXAMPLES

LIST OF FIGURES